

ABSTRACT

A printed wiring board manufacturing method is provided which is so constituted that when a carbon dioxide laser is used to form holes such as via holes in a copper clad laminate, copper foils and resin layers may be processed at the same time, without having to perform an etching treatment on the copper foil. Namely, a carbon dioxide laser is used to form recess portions such as via holes in a copper clad laminate, followed by plating to form interlayer electrical connections, forming etching resist layers, and exposing and developing the etching resist layers, thereby effecting a circuit etching treatment. In particular, the copper clad laminate is a laminate formed by using waved copper foils to form external copper foils.

054501 054501 054501